

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-25. (Canceled)

26. (Withdrawn) A method comprising:

forming a protective coating of polypara-xylylene on an exposed surface of an integrated power device, including forming the protective coating on a conductive termination connected to a semiconductor in the power device; and

cutting a window in the protective coating using a laser to expose the termination.

27. (Withdrawn) A method comprising:

forming a protective coating on an expose surface of an electronic device, including forming the protective coating on a conductive termination connected to a circuit element in the electronic device;

making a window in the protective coating to expose the termination;

applying solder to the portion of the conductive termination exposed by the window in the protective coating; and

encapsulating the electronic device in a potting material.

28. (Withdrawn) A method for use with an electronic device having a conductive termination pad and an electronic component connected to the pad, the method comprising:

applying a protective coating to surfaces of the termination pad and the electronic component;

cutting a window in the protective coating to expose the termination pad; and

flowing solder into the window to make electrical connection between the solder pad and a circuit.

29. (Canceled)

30. (Currently Amended) An apparatus comprising:

an electronic device having an outer surface and a first conductive termination on the surface for connection to an external circuit;

a protective, conformal coating on the outer surface of the electronic device; and

a first window formed in the protective coating ~~to expose~~ that exposes at least a portion of the first conductive termination without exposing any other conductive terminations on the surface of the electronic device, wherein the exposed portion of the conductive termination is recessed in the window of the conformal coating, the window defining a boundary for a solder connection between the external circuit and the first conductive termination.

31. (Previously Presented) The apparatus of claim 30 wherein the coating comprises a uniform thickness.

32. (Previously Presented) The apparatus of claim 30 wherein the coating conforms to the geometric configuration of the electronic device.

33. (Previously Presented) The apparatus of claim 30 wherein the coating comprises a polymer.

34. (Previously Presented) The apparatus of claim 33 wherein the polymer comprises poly-paraxylylene.

35. (Previously Presented) The apparatus of claim 30 wherein the electronic device comprises an integrated power device (IPD).

36. (Previously Presented) The apparatus of claim 30 wherein the electronic device further comprises a semiconductor.

37. (Previously Presented) The apparatus of claim 30 wherein the electronic device further comprises power semiconductor.

38. (Canceled)

39. (Currently amended) The apparatus of claim 30 wherein the electronic device further comprises a second conductive termination and the protective coating comprises a second window that exposes a portion of the second conductive termination, wherein the exposed portion of the second conductive termination is recessed within the second window in the protective coating, the second window defining a boundary for a second solder connection between the external circuit and the second conductive termination.

40. (New) The apparatus of claim 39 wherein the second conductive termination comprises a plurality of conductive terminations, the second window comprises a plurality of windows exposing a respective portion of a respective one of the plurality of conductive terminations, wherein each exposed respective portion is recessed within a respective one of the plurality of windows in the protective coating, each respective one of the plurality of windows defining a boundary for a respective solder connection between the external circuit and the respective one of the plurality of conductive terminations.